

DOC.IV-7 EDITION: 2025-Q3

PRODUCT CATALOG

FIBER OTICS & PHOTONICS



SCOPE: Optoelectronic Components & Solutions

APPLICATIONS: Optical
Communication, Consumer &
Automotive

KEY TECH: VCSELs, PIN Photodiodes, SiGe BICMOS



01. WELCOME TO VI SYSTEMS

VI SYSTEMS (VIS) DEVELOPS AND MANUFACTURES CUTTING-EDGE OPTOELECTRONIC COMPONENTS FOR COMMUNICATION, CONSUMER, AND AUTOMOTIVE APPLICATIONS. LOCATED IN THE HEART OF BERLIN, WE ARE A FABLESS COMPANY SPECIALIZING IN ULTRA-FAST SOLUTIONS FOR OPTICAL INTERCONNECTS AND SENSORS.

OUR PORTFOLIO INCLUDES VERTICAL CAVITY SURFACE-EMITTING LASERS (VCSELS) AND PIN PHOTODIODES DELIVERING SPEEDS UP TO 224 GBPS PER CHANNEL, ALONGSIDE DRIVER AND AMPLIFIER ICS OPERATING UP TO 56 GBPS. OUR LATEST GENERATION COMPONENTS ENABLE ENERGY-EFFICIENT 400 GBPS PAM-4 TRANSMISSION USING SHORT WAVE DIVISION MULTIPLEXING (SWDM).

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03. TECHNOLOGY & SERVICES

INTEGRATED OPTICAL SOLUTIONS

VIS CUSTOMIZES STATE-OF-THE-ART SIGE BICMOS INTEGRATED CIRCUITS TO MATCH ULTRAHIGH-SPEED VCSEL TRANSMITTER AND PIN RECEIVER COMPONENTS.

BOTH KEY ELEMENTS ARE ASSEMBLED IN A PROPRIETARY HIGH-FREQUENCY DESIGN DELIVERING OUTSTANDING PERFORMANCE OVER A WIDE TEMPERATURE RANGE.

KEY ADVANTAGES:

- HIGH SPEED PERFORMANCE
- LOW POWER CONSUMPTION
- SMALL FOOTPRINT DESIGN
- HIGH RELIABILITY
- LOW COST MANUFACTURING

OUR UNIQUE SELLING POINT IS THE COMBINATION OF MICRO-ASSEMBLY INTEGRATION OF ADVANCED ELECTRO-OPTIC COMPONENTS, DEVELOPMENT OF HIGH-SPEED ICS AND MODULATION APPROACHES.

VIS OPERATES A FABLESS MODEL ENSURING RELIABILITY AND SCALABILITY.

INTEGRATED VCSEL
DRIVER WITH VCSEL
CHIP PHOTO

CONCEPTUAL GRAPHIC:
ICS + OPTICAL
COMPONENTS
INTEGRATION

04. WAFER MAPPING & HIGH-FREQUENCY TESTING

WAFER MAPPING SERVICES

VIS'S SEMI-AUTOMATIC PROBER STATION
PERFORMS HIGH-SPEED ELECTRICAL AND
OPTICAL TESTING EARLY IN THE
MANUFACTURING PROCESS, REDUCING COSTS
BY ELIMINATING OUT-OF-SPEC WAFERS.

FULL WAFER CHARACTERISATION: 100% CHARACTERISATION OF 2"-8" WAFERS USING AN ALIGNMENT CAMERA WITH PATTERN RECOGNITION; AUTOMATIC ALIGNMENT TO CHIPS; TEMPERATURE RANGE 25°C-150°C.

MEASURED PARAMETERS:

- L/I/V CURVES
- THRESHOLD CURRENT
- SLOPE EFFICIENCY
- OPTICAL SPECTRUM
- PHOTODIODE SENSITIVITY
- REVERSE BIAS AND DARK CURRENT

EMISSION ANALYSIS: NEARFIELD AND FARFIELD
ANALYSIS FOR EMITTING DIAMETER, MODE
CHARACTERISTICS, POLARIZATION AND
ANGULAR POWER DISTRIBUTION.

SEMI-AUTOMATIC WAFER PROBER AND ALIGNMENT CAMERA PHOTO

HIGH-FREQUENCY TEST & CHARACTERISATION

THE HIGH-FREQUENCY LAB ANALYSES
ELECTRO-OPTICAL PERFORMANCE USING A
SINE-WAVE GENERATOR UP TO 38 GHZ WITH A
70 GHZ SAMPLING OSCILLOSCOPE.

LABORATORY CAPABILITIES:

- 32 GHZ DETECTOR COVERS 700— 1600 NM
- EYE-DIAGRAM AND MODULATION TESTS UP TO 128 GBIT/S
- PRBS7/PRBS31 PATTERN GENERATION
- PHOTODETECTOR MODULES UP TO 112 GBIT/S AT 850 NM

HIGH-FREQUENCY TEST LABORATORY SETUP PHOTO



06. OPTICAL & MECHANICAL INSPECTION, MODELLING & SIMULATION

OPTICAL & MECHANICAL INSPECTION

THE LABORATORY'S OPTICAL MICROSCOPES UP TO 1000×
MAGNIFICATION AND THICKNESS ANALYSIS TECHNOLOGY
RESOLVING 0.1 MM (HORIZONTAL) AND 0.5 MM (VERTICAL).

MICROPROBER STATION: ON-WAFER CHARACTERISATION OVER A WIDE TEMPERATURE RANGE; STATIC TESTS MEASURE FORWARD/REVERSE VOLTAGE, CURRENT AND DIFFERENTIAL RESISTANCE.

OPTICAL PARAMETERS:

- POWER
- SPECTRUM
- SENSITIVITY
- EFFICIENCY
- THRESHOLD CURRENT
- SLOPE EFFICIENCY
- AMPLIFICATION

ADVANCED STUDIES: COMPLEX ANALYSES USE FIB, SEM AND TEM WITH EXTERNAL PARTNERS.

MODELLING & SIMULATION

THERMAL MODELLING OF SEMICONDUCTOR PACKAGES USES MODERN FEA/CFD TOOLS INTEGRATED WITH MECHANICAL CAD.

VCSEL SIMULATION: MODELLING OF VCSEL OPTICAL MODES (FUNDAMENTAL AND EXCITED MODES) AND THERMAL DISTRIBUTIONS, WHICH INFORM DESIGN IMPROVEMENTS.

STEREO MICROSCOPE WITH TEMPERATURE CHUCK

HIGH-RESOLUTION OPTICAL MICROSCOPE

TEM ANALYSIS PHOTO

THERMAL
DISTRIBUTION
GRAPHIC



06. VCSEL TRANSMITTER MODULES



V25-850M	
DATA RATE	28 GE
WAVELENGTH	850 N

28 GBPS (NRZ) 850 NM 50/125 MM DATASHEET &

CHIPS



V50-850M

DATA RATE 56 GBPS (PAM-4) WAVELENGTH 850 NM

FIBER TYPE 50/125 MM

DATASHEET &



VM100-850M

DATA RATE 112 GBPS (PAM-4)

WAVELENGTH 850 NM FIBER TYPE 50/125 MM

DATASHEET &



T56-850

DATA RATE 56 GBPS (NRZ)

WAVELENGTH 850 NM FIBER TYPE 50/125 MM

DATASHEET &



V25-1550M

WAVELENGTH 1550 NM
DATA RATE 25 GBPS (NRZ)

FIBER TYPE 9/125 MM

DATASHEET &



07. OPTICAL RECEIVERS & PHOTODETECTORS



R56-850

INPUT 700-870 NM

WAVELENGTH

DATA RATE (NRZ) 56 GBPS FIBER TYPE 50/125 MM DATASHEET &



D30-850M

3 DB BANDWIDTH > 30 GHZ 840-1650 NM WAVELENGTH FIBER TYPE 50/125 MM

DATASHEET &



D60M FC

INPUT 400-1650 NM

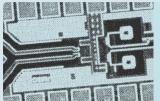
WAVELENGTH

3 DB BANDWIDTH > 60 GHZ FIBER TYPE MMF/SMF



08. INTEGRATED CIRCUITS (ICS)

HIGH SPEED VCSEL DRIVERS



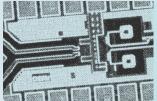
A56-230C

UP TO 100 GBPS

SUPPLY VOLTAGE 3.3 V 200 MW

DISSIPATION

DATASHEET &



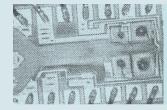
A56-105C

DATA RATE UP TO 56 GBPS

SUPPLY VOLTAGE 3.3 V **POWER** 105 MW

DISSIPATION

DATASHEET &



T56-250C

UP TO 56 GBPS (NRZ) DATA RATE

DIFFERENTIAL 3.0 KΩ

GAIN

POWER 150 MW



09. ULTRA HIGH-SPEED VCSEL CHIPS

SERIES: VM100

VM100 850 CHIP TYPE WAVELENGTH CONTACT	MULTI-MODE 840-860 NM GSG	DATASHEET
VM100 880 CHIP TYPE WAVELENGTH CONTACT	MULTI-MODE 870-890 NM GSG	DATASHEET
VM100 910 CHIP TYPE WAVELENGTH CONTACT	MULTI-MODE 900-920 NM GSG	DATASHEET
VM100 940 CHIP TYPE WAVELENGTH CONTACT	MULTI-MODE 930-950 NM GSG	DATASHEET



10. ULTRA HIGH-SPEED VCSEL CHIPS

CONTACT

SERIES: VM100 (MA-SM / QSM)



VM100 850	MA-SM	
CHIP TYPE	MA-SM	
WAVELENGTH	840-860	NM

GSG

DATASHEET &



VM100 880	MA-SM	
CHIP TYPE	MA-SM	
WAVELENGTH	870-890	NΜ
CONTACT	GSG	

DATASHEET &



VM100 910	MA-SM	
CHIP TYPE	MA-SM	
WAVELENGTH	900-920	NM
CONTACT	GSG	

DATASHEET &



VM100 940 CHIPTYPE	MA-SM MA-SM	
WAVELENGTH	930-950 NM	1
CONTACT	GSG	

DATASHEET &



VM100 850	QSM	
CHIP TYPE	QSM	
WAVELENGTH	840-860	NM
CONTACT	GSG	

DATASHEET &



VM100 910	QSM	
CHIP TYPE	QSM	
WAVELENGTH	900-920 NM	1
CONTACT	GSG	



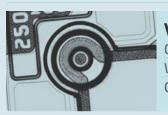
11. HIGH-SPEED VCSEL CHIPS

SERIES: V50 / VM50 / V25



V50 850	
CHIP TYPE	MULTI-MODE
WAVELENGTH	840-860 NM
CONTACT	SG / GS





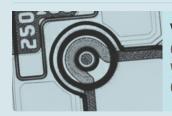
VM50 940	
CHIP TYPE	MULTI-MODE
WAVELENGTH	930-950 NM
CONTACT	GSG





V25	940	HP	MA			
FEAT	JRE		HIGH	POV	VER	(LIFI)
WAVE	LENGT	ГН	930-9	950	NM	
CONT	ACT		SG /	GS		





VM50 850	
CHIP TYPE MU	JLTI-MODE
WAVELENGTH 84	10-860 NM
CONTACT GS	SG

DATASHEET &



V25 850 HI	
FEATURE	HIGH TEMP (125°C)
WAVELENGTH	840-860 NM
CONTACT	SG / GS



12. HIGH-SPEED PHOTODIODES (PDS)

SWDM-OPTIMIZED



D40	SWDM
CONT	ACT TYPE

GSG DIAMETER 20 MM BANDWIDTH ~40 GHZ DATASHEET &



D35 SWDM

CONTACT TYPE GSG DIAMETER 25 MM **BANDWIDTH** ~35 GHZ DATASHEET &



D30 SWDM

CONTACT TYPE GSG ~23 MM DIAMETER ~30 GHZ BANDWIDTH

DATASHEET &



D70 SWDM

CONTACT TYPE GSG ~25 MM DIAMETER BANDWIDTH ~70 GHZ DATASHEET &



D400G

CONTACT TYPE **GSG** DIAMETER ~16 MM ~60 GHZ (25Ω) BANDWIDTH



13. CONTACT INFORMATION

FOR ADDITIONAL INFORMATION OR TO RECEIVE A QUOTATION, PLEASE CONTACT OUR SALES DEPARTMENT.

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